

Mar-10-03 01:57pm From:HOGAN and HARTSON

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T-153 P.006/042 F-548

PATENT  
81877.0012

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Seiyo Nakashima et al.

Serial No: 09/816,643

Filed: March 23, 2001

For: SUBSTRATE PROCESSING  
APPARATUS AND SUBSTRATE  
PROCESSING METHOD

Art Unit: 1763

Examiner: Kackar, Ram N

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AMENDMENT

Commissioner for Patents  
Washington, D.C. 20231

Dear Sir:

In response to the Office Action dated September 9, 2002, please amend the  
above-referenced application as follows:

IN THE SPECIFICATION:

Please replace the section of the specification entitled SUMMARY OF THE  
INVENTION starting on page 3, line 5, and continuing through page 6, line 23,  
with the following text:

"SUMMARY OF THE INVENTION"

According to a first aspect of the present invention, there is provided a  
substrate processing apparatus, including:

a processing chamber;

a susceptor on which a substrate is placed; and

a heating unit disposed below the susceptor for heating the substrate

placed on the susceptor, wherein

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